



the contact area increasing portion is formed of an extension portion-forming member brought in contact with the bump or the pattern forming surface located in a vicinity of the bump when the contact area is increased; and

the extension portion-forming member is pressurized against the bump or the pattern forming surface located in the vicinity of the bump.

51.(Original) A semiconductor device-mounted component manufacturing method as claimed in claim 50, wherein, when the extension portion-forming member has a cylindrical shape, a projecting portion is formed as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member.

52.(Original) A semiconductor device-mounted component manufacturing method as claimed in claim 50, wherein, when the extension portion-forming member has a rugged portion at its tip, a rugged portion is formed as the contact area increasing portion on the bump formed by a pressurizing operation for performing pressurization with the extension portion-forming member.

53.(Original) A semiconductor device-mounted component manufacturing method as claimed in claim 50, wherein, when the extension portion-forming member has a cylindrical shape, a contact area increasing groove is formed in the vicinity of the bump by pressurizing the pattern forming surface in the vicinity of the bump by a pressurizing operation for performing pressurization with the extension portion-forming member, thus exposing the bump from the base material.

54.(Cancelled)